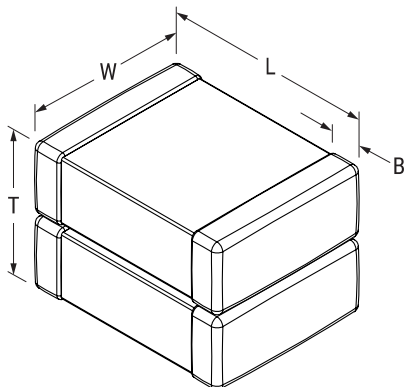


KONNEKT KC-Link, Ceramic, 200 uF, 10%, 500 VDC, COG, 2-Chip Standard Orientation.


Dimensions

L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	5mm +/-0.4mm
B	0.6mm +/-0.35mm

Packaging Specifications

Weight:	600 mg
Packaging:	T&R, 180mm
Packaging Quantity:	300

General Information

Series:	KONNEKT KC-Link
Style:	KONNEKT
Description:	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features:	Ultra-Stable, Low Loss
RoHS:	Yes
Termination:	Tin
AEC-Q200:	No
Notes:	2-Chip Standard Orientation.
Chip Size:	2220
MSL:	1

Specifications

Capacitance:	200 uF
Measurement Condition:	1 kHz 1.0Vrms
Capacitance Tolerance:	10%
Voltage DC:	500 VDC
Dielectric Withstanding Voltage:	750 VDC
Temperature Range:	-55/+150°C
Temperature Coefficient:	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor:	0.1% 1 kHz 1.0Vrms
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	5 MOhms